Application No. 10/684,072
Response to Official Action

VIA FACSIMILE TRANSMISSION – OFFICIAL
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In the Specification

Page 9 of the specification, lines 4-15, please replace the present paragraph with the following amended paragraph.

FIG. 9 illustrates the resulting electrical circuit model of a given conductor path in an integrated circuit device package of the present invention including an equivalent circuit model 16' for representing a typical lead frame conductor 16. An output signal V_{OUT} from the integrated circuit 12 feeds into an output buffer 24 which is externally connected through an IC bonding wire pad 20. The bonding wire 20 exhibits a small series inductance L_B which is small relative to the inductance L_F of the ferrite microbead 30. The lead frame conductor 16 exhibits a characteristic lumped series inductance L_{OUT} and shunt capacitance C_{OUT}, the effects of which are negligible compared to the inductance L_F of the microbead 30, and extends through the encapsulating medium 14. The effects of inductance L_{OUT} and capacitance C_{OUT} may be further reduced by the blending of ferrite with the encapsulation material 14. The lead frame conductor 16 connects to an external pin 18_{OUT} on the exterior of the device package 10.

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